

N- and P-Channel 20-V (D-S) MOSFET

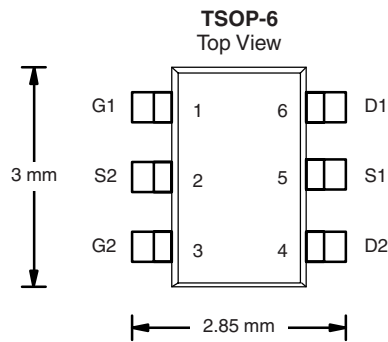
PRODUCT SUMMARY			
	V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
N-Channel	20	0.080 at $V_{GS} = 4.5$ V	3.0
		0.100 at $V_{GS} = 2.5$ V	2.6
		0.128 at $V_{GS} = 1.8$ V	2.3
P-Channel	- 20	0.145 at $V_{GS} = - 4.5$ V	- 2.2
		0.200 at $V_{GS} = - 2.5$ V	- 1.8
		0.300 at $V_{GS} = - 1.8$ V	- 1.5

FEATURES

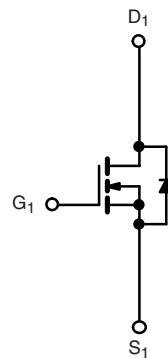
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFETs: 1.8 V Rated
- Compliant to RoHS Directive 2002/95/EC



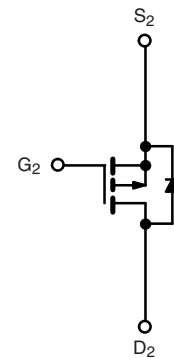
RoHS
COMPLIANT
HALOGEN
FREE
Available



Ordering Information: Si3588DV-T1-E3 (Lead (Pb)-free)
Si3588DV-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted							
Parameter	Symbol	N-Channel		P-Channel		Unit	
		5 s	Steady State	5 s	Steady State		
Drain-Source Voltage	V_{DS}	20		- 20		V	
Gate-Source Voltage	V_{GS}	± 8					
Continuous Drain Current ($T_J = 150$ °C) ^a	I_D	$T_A = 25$ °C	3.0	2.5	- 2.2	- 0.57	A
		$T_A = 70$ °C	2.3	2.0	- 1.8	- 1.5	
Pulsed Drain Current	I_{DM}	± 8				A	
Continuous Source Current (Diode Conduction) ^a	I_S	1.05	0.75	- 1.05	- 0.75		
Maximum Power Dissipation ^a	P_D	$T_A = 25$ °C	1.15	0.83	1.15	0.083	W
		$T_A = 70$ °C	0.73	0.53	0.73	0.53	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	R_{thJA}	$t \leq 5$ s	93	110	°C/W
		Steady State	130	150	
Maximum Junction-to-Foot (Drain)	R_{thJF}	90	90		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	N-Ch	0.45			V
		$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	P-Ch	-0.45			
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 8\text{ V}$	N-Ch			± 100	nA
		$V_{DS} = 0\text{ V}, V_{GS} = \pm 8\text{ V}$	P-Ch			± 100	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}$	N-Ch			1	μA
		$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}$	P-Ch			-1	
		$V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}, T_J = 85\text{ }^\circ\text{C}$	N-Ch			10	
		$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}, T_J = 85\text{ }^\circ\text{C}$	P-Ch			-10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 4.5\text{ V}$	N-Ch	5			A
		$V_{DS} \leq -5\text{ V}, V_{GS} = -4.5\text{ V}$	P-Ch	-5			
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}, I_D = 3\text{ A}$	N-Ch		0.064	0.080	Ω
		$V_{GS} = -4.5\text{ V}, I_D = -2.2\text{ A}$	P-Ch		0.115	0.145	
		$V_{GS} = 2.5\text{ V}, I_D = 2.6\text{ A}$	N-Ch		0.080	0.100	
		$V_{GS} = -2.5\text{ V}, I_D = -1.8\text{ A}$	P-Ch		0.163	0.200	
		$V_{GS} = 1.8\text{ V}, I_D = 2.3\text{ A}$	N-Ch		0.104	0.128	
		$V_{GS} = -1.8\text{ V}, I_D = -1.0\text{ A}$	P-Ch		0.240	0.300	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 5\text{ V}, I_D = 3\text{ A}$	N-Ch		9		S
		$V_{DS} = -5\text{ V}, I_D = -2.2\text{ A}$	P-Ch		5		
Diode Forward Voltage ^a	V_{SD}	$I_S = 1.05\text{ A}, V_{GS} = 0\text{ V}$	N-Ch		0.8	1.1	V
		$I_S = -1.05\text{ A}, V_{GS} = 0\text{ V}$	P-Ch		-0.8	-1.1	
Dynamic^b							
Total Gate Charge	Q_g	N-Channel $V_{DS} = 10\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 3\text{ A}$	N-Ch		5	7.5	nC
Gate-Source Charge	Q_{gs}		P-Ch		5	7.5	
Gate-Drain Charge	Q_{gd}	P-Channel $V_{DS} = -10\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -2.2\text{ A}$	N-Ch		0.65		
			P-Ch		1.0		
Turn-On Delay Time	$t_{d(on)}$	N-Channel $V_{DD} = 10\text{ V}, R_L = 10\text{ }\Omega$ $I_D \cong 0.5\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 6\text{ }\Omega$	N-Ch		12	20	ns
Rise Time	t_r		P-Ch		12	20	
Turn-Off Delay Time	$t_{d(off)}$	P-Channel $V_{DD} = -4\text{ V}, R_L = 8\text{ }\Omega$ $I_D \cong -1\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 6\text{ }\Omega$	N-Ch		30	50	
			P-Ch		29	50	
Fall Time	t_f		N-Ch		28	50	
			P-Ch		24	45	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 1.05\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}$	N-Ch		20	40	
		$I_F = -1.05\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}$	P-Ch		20	40	

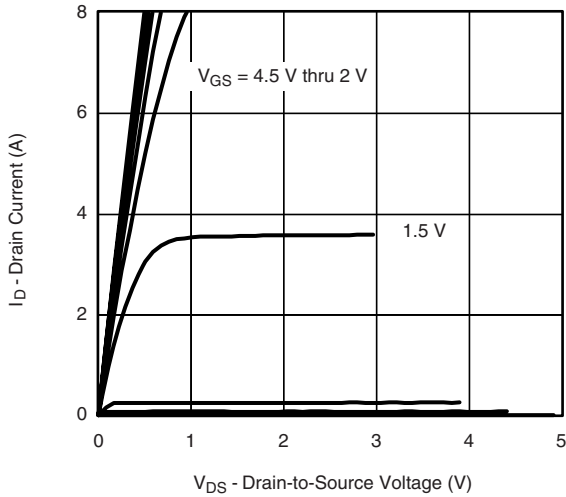
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

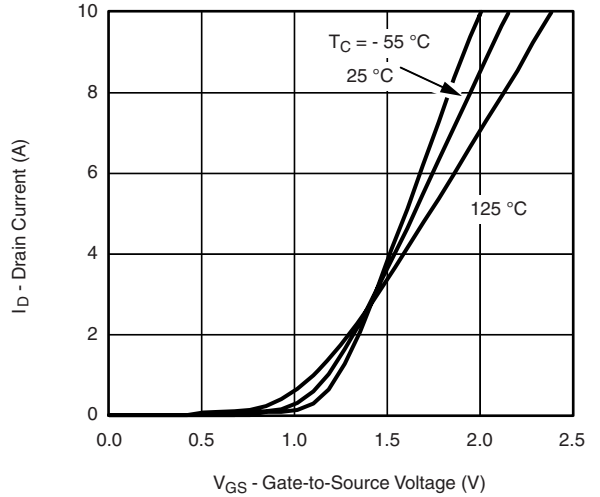
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

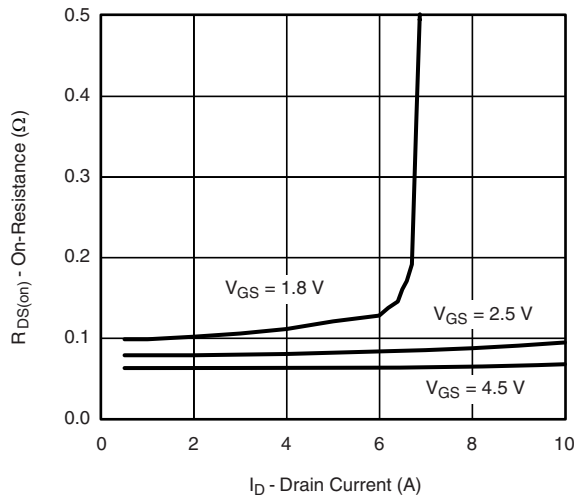
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



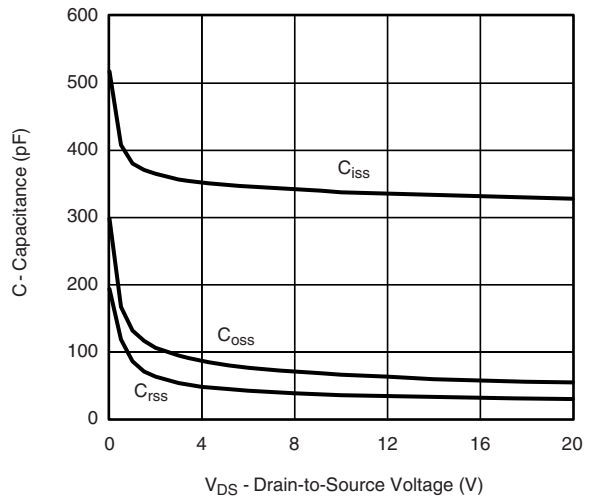
Output Characteristics



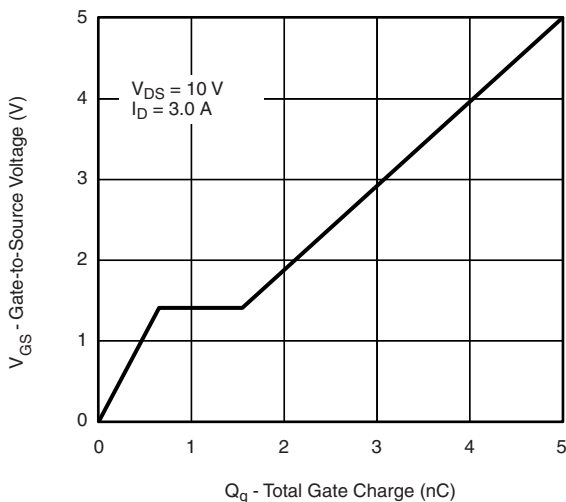
Transfer Characteristics



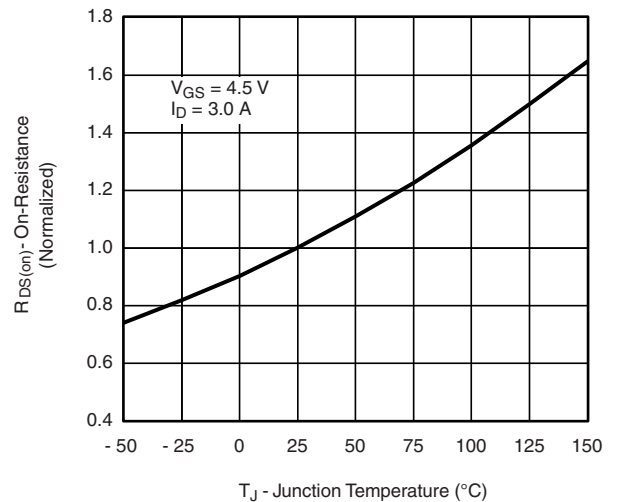
On-Resistance vs. Drain Current



Capacitance

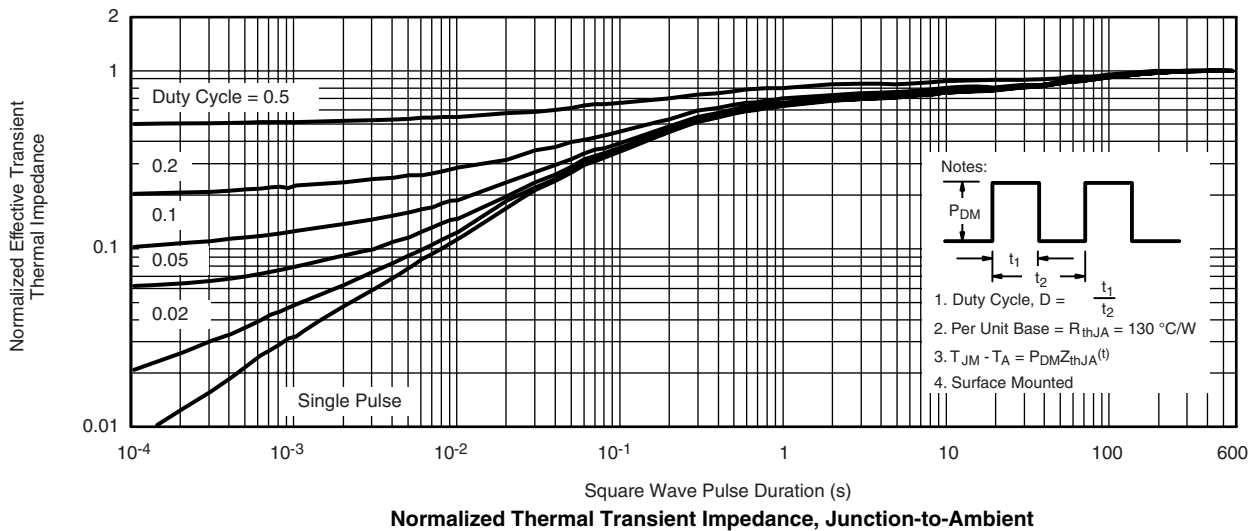
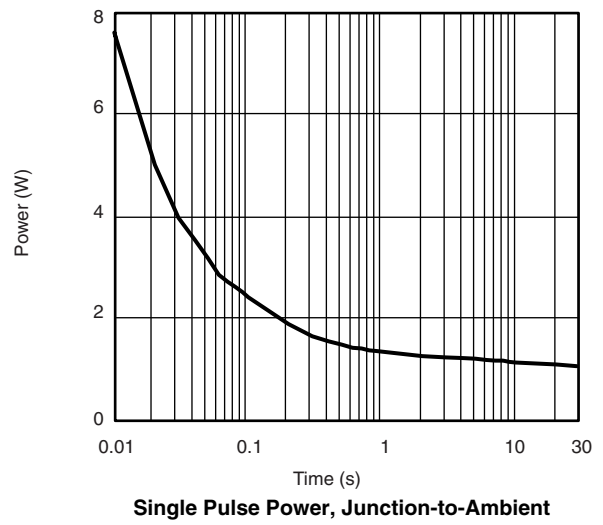
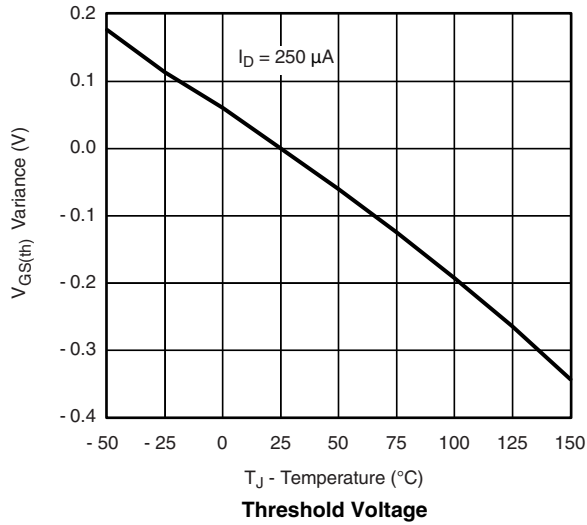
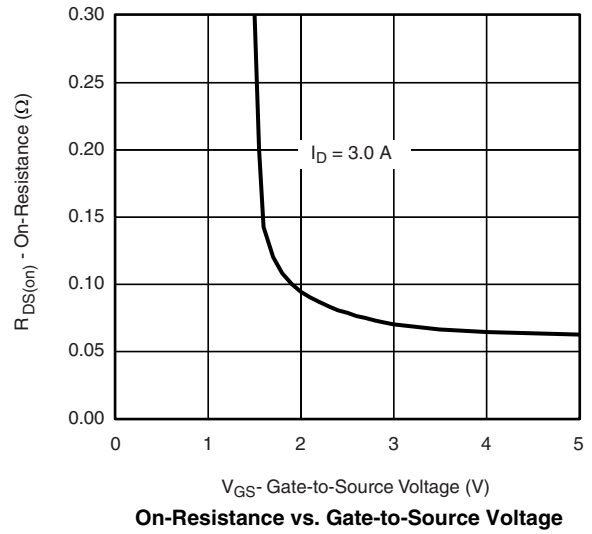
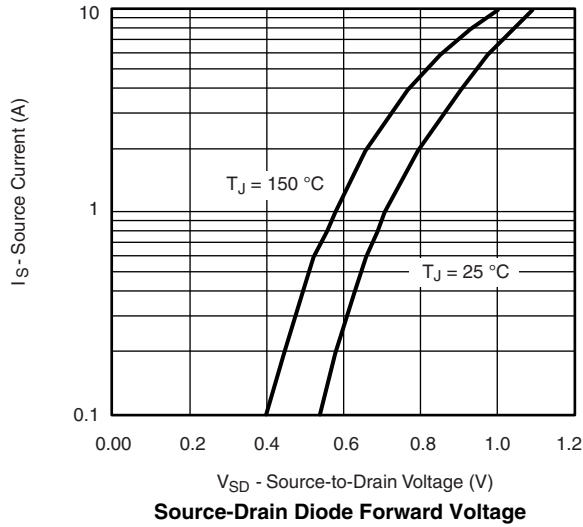


Gate Charge

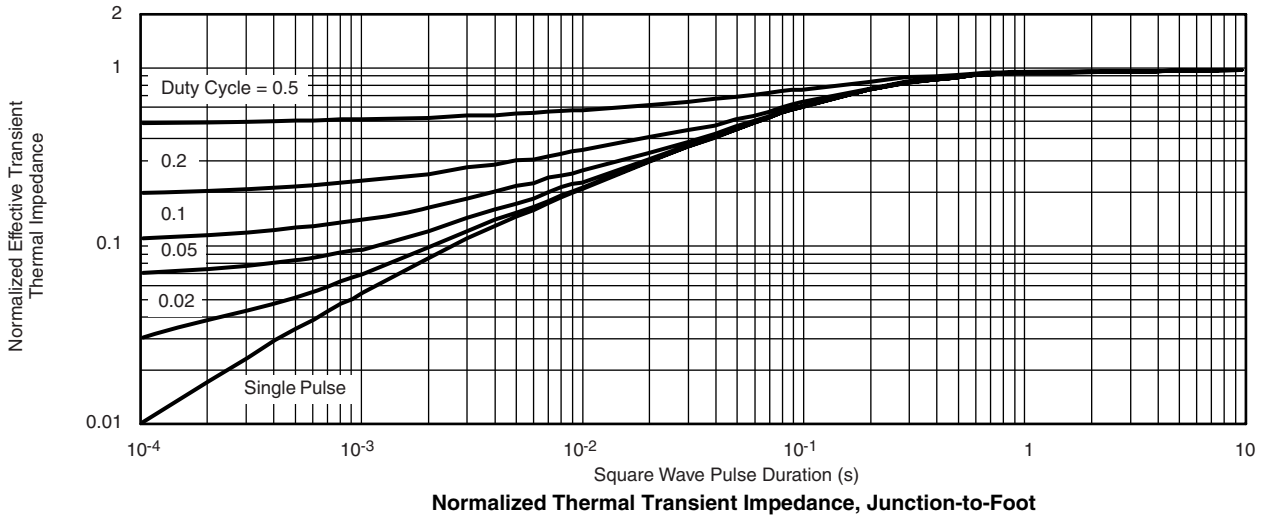


On-Resistance vs. Junction Temperature

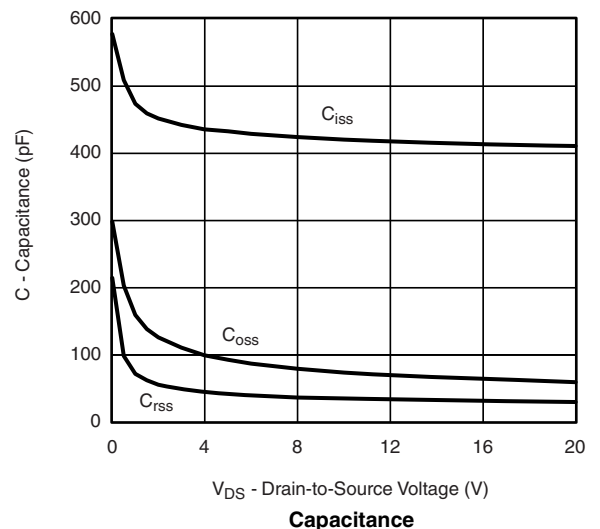
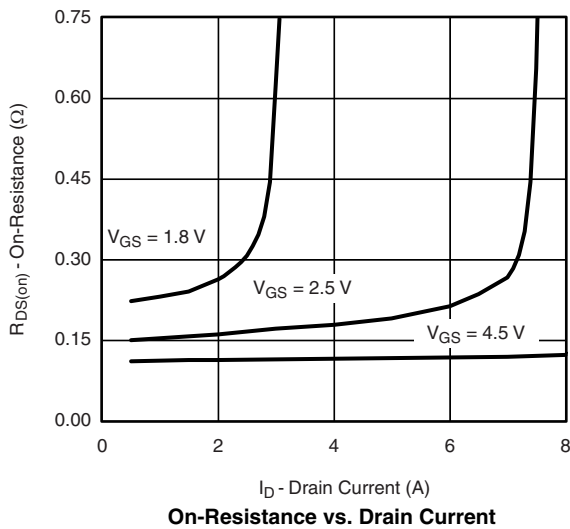
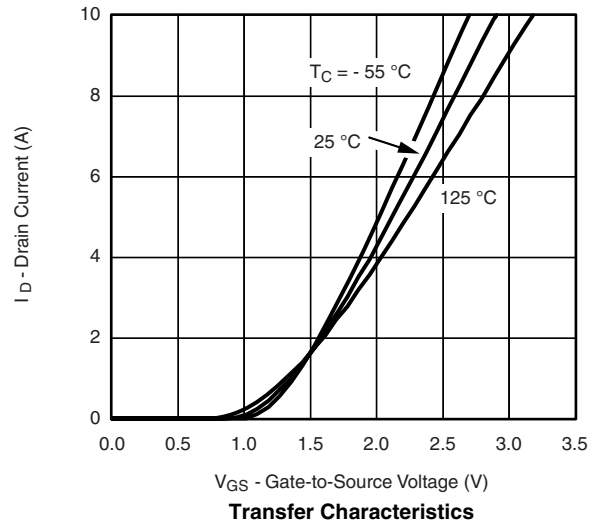
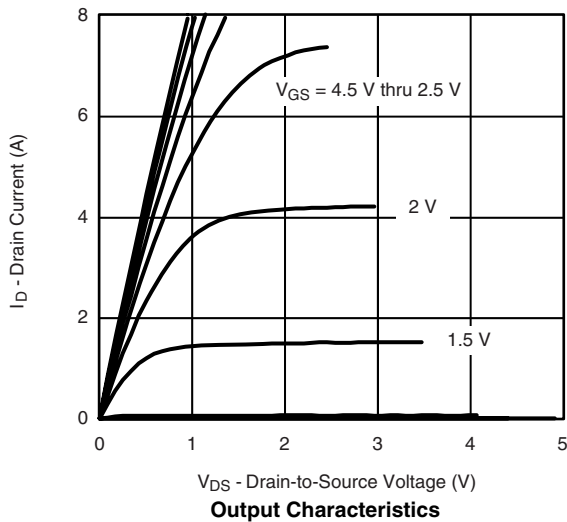
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



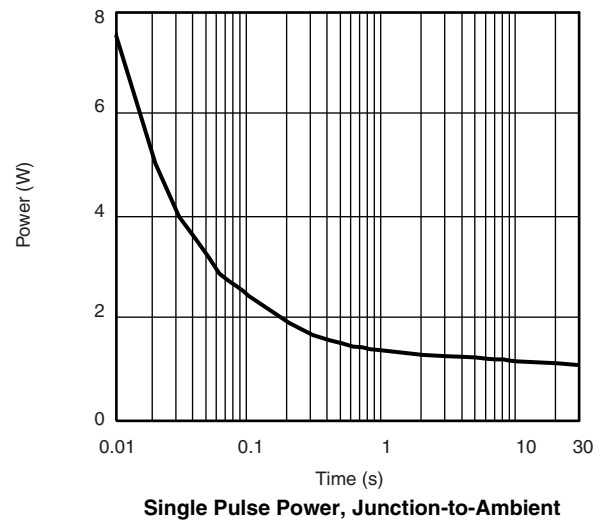
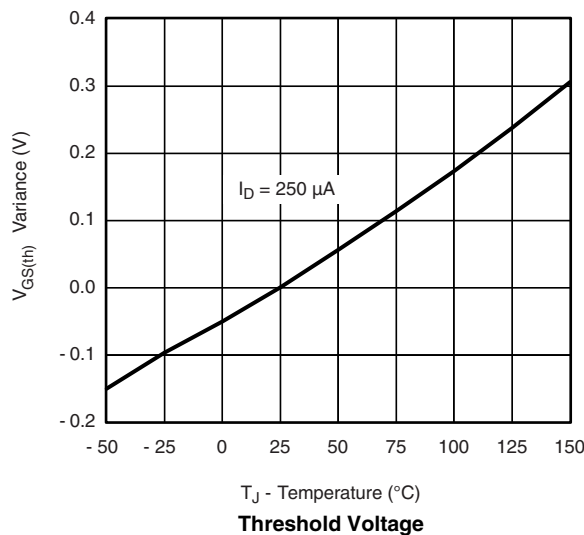
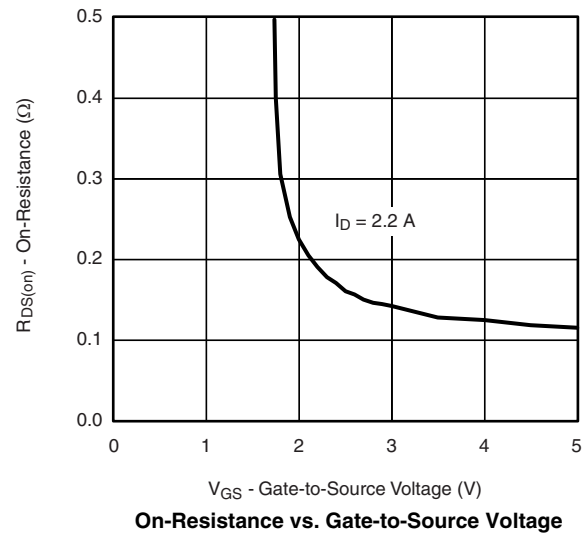
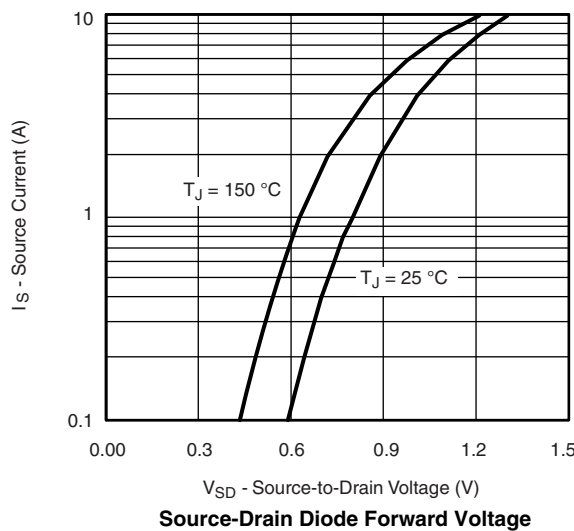
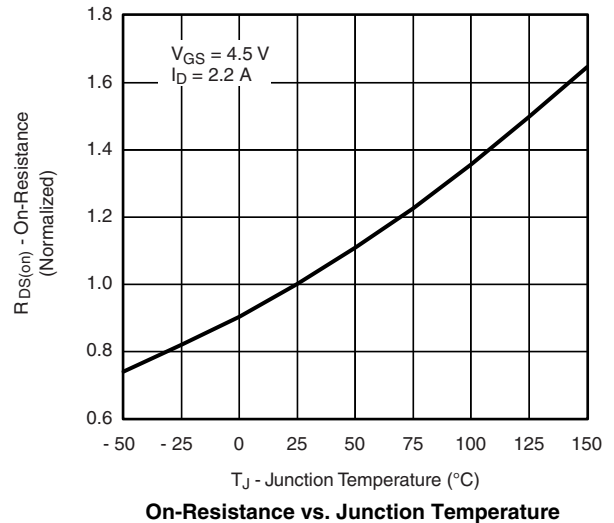
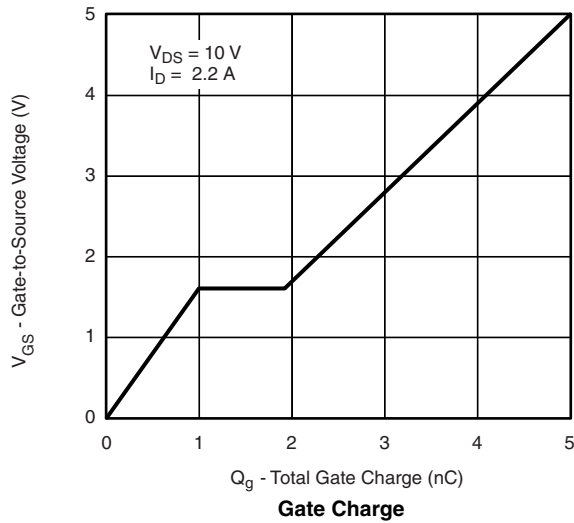
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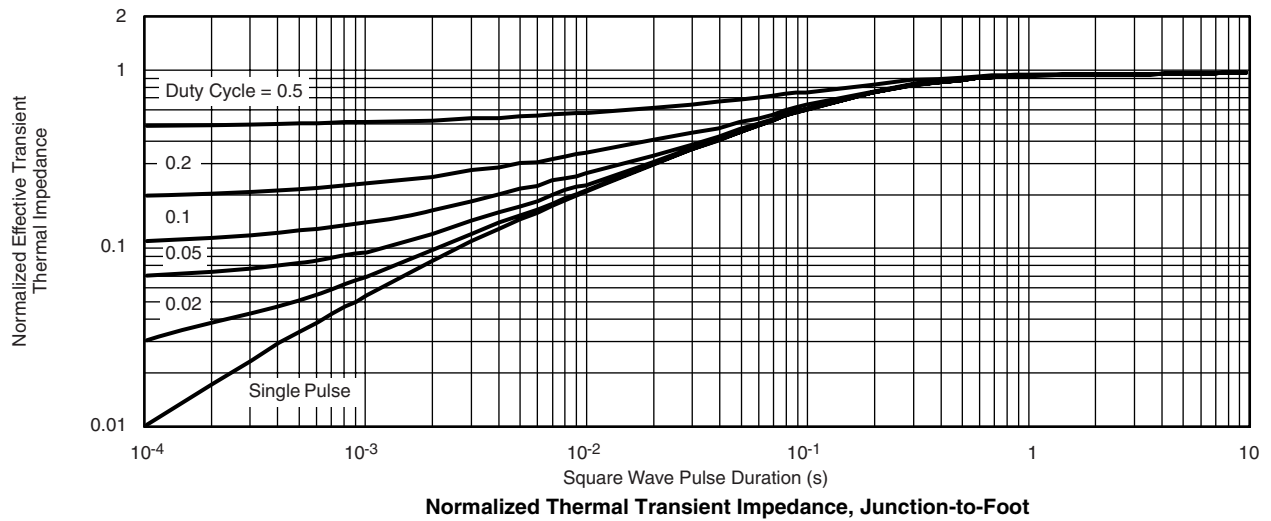
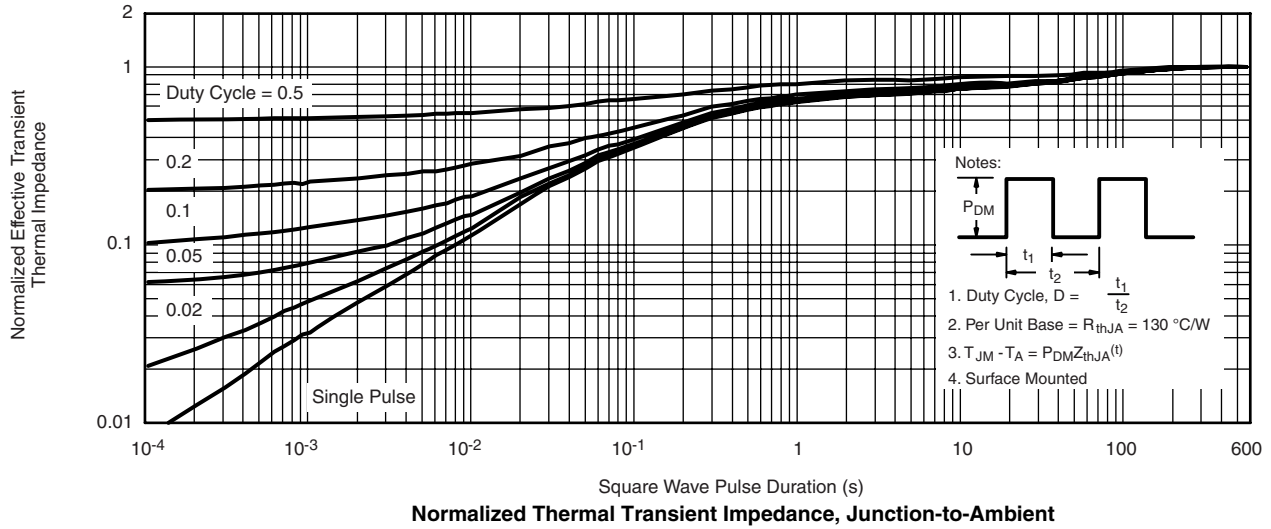
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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